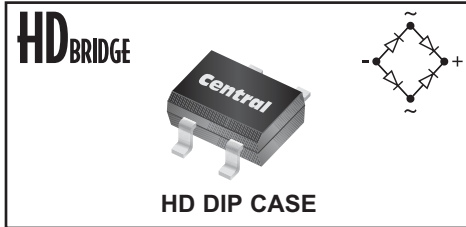


CBRHDSH2-100
SURFACE MOUNT
HIGH DENSITY
2 AMP SILICON
SCHOTTKY BRIDGE RECTIFIER



• Device is **Halogen Free** by design



www.centralemi.com

DESCRIPTION:

The CENTRAL SEMICONDUCTOR CBRHDSH2-100 is a full wave bridge rectifier mounted in a durable epoxy surface mount case, utilizing glass passivated chips.

MARKING CODE: CSH10

FEATURES:

- Low Leakage Current (700nA TYP @ V_{RRM})
- High 2.0A Current Rating
- Low V_F Schottky Diodes (840mV MAX @ $I_F=2.0A$)

MAXIMUM RATINGS: ($T_A=25^\circ C$ unless otherwise noted)

Peak Repetitive Reverse Voltage
 DC Blocking Voltage
 RMS Reverse Voltage
 Average Forward Current ($T_A=75^\circ C$)
 Peak Forward Surge Current (8.3ms)
 Operating Junction Temperature
 Storage Temperature

SYMBOL

V_{RRM} 100
 V_R 100
 $V_{R(RMS)}$ 70
 I_O 2.0
 I_{FSM} 50
 T_J -50 to +125
 T_{stg} -50 to +150

UNITS

V
 V
 V
 A
 A
 $^\circ C$
 $^\circ C$

ELECTRICAL CHARACTERISTICS PER DIODE: ($T_A=25^\circ C$ unless otherwise noted)

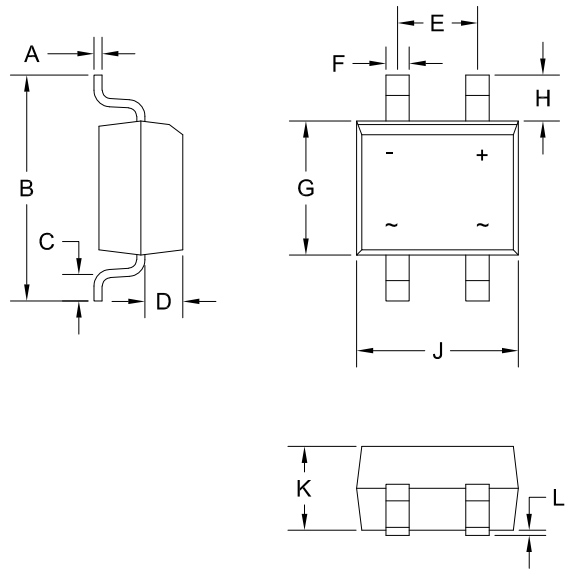
SYMBOL	TEST CONDITIONS	TYP	MAX	UNITS
I_R	$V_R=100V$	0.70	4.0	μA
V_F	$I_F=500mA$	610		mV
V_F	$I_F=1.0A$	700		mV
V_F	$I_F=2.0A$	770	840	mV
C_J	$V_R=4.0V$, $f=1.0MHz$		250	pF

CBRHDSH2-100

SURFACE MOUNT
HIGH DENSITY
2 AMP SILICON
SCHOTTKY BRIDGE RECTIFIER



HD DIP CASE - MECHANICAL OUTLINE



R3

SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.006	0.014	0.15	0.35
B	-	0.275	-	7.00
C	0.027	0.043	0.70	1.10
D	0.035	0.051	0.90	1.30
E	0.090	0.106	2.30	2.70
F	0.019	0.031	0.50	0.80
G	0.146	0.165	3.70	4.20
H	0.051	0.067	1.30	1.70
J	0.177	0.193	4.50	4.90
K	0.090	0.106	2.30	2.70
L	0.000	0.008	0.00	0.20

HD DIP (REV: R3)

MARKING CODE: CSH10

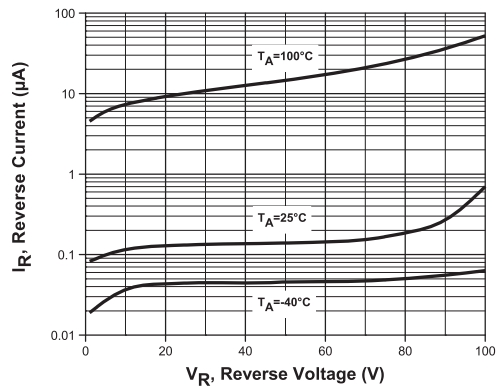
R4 (19-August 2020)

CBRHDSH2-100
SURFACE MOUNT
HIGH DENSITY
2 AMP SILICON
SCHOTTKY BRIDGE RECTIFIER

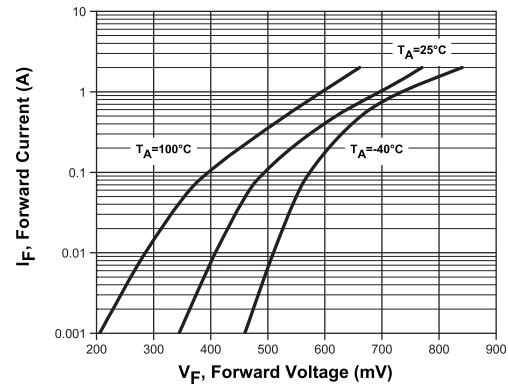


TYPICAL ELECTRICAL CHARACTERISTICS

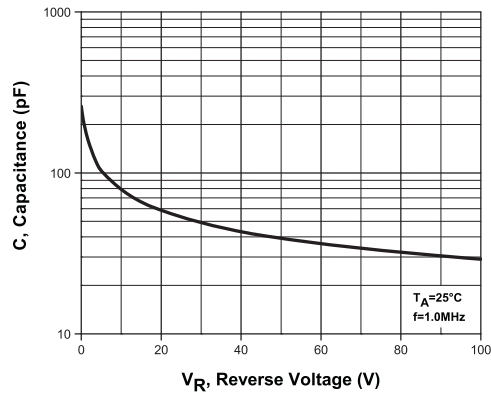
Typical Per Diode Leakage Current



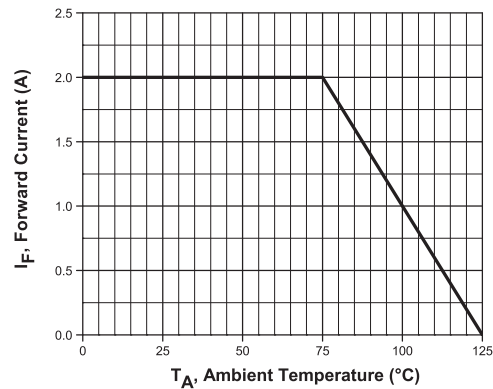
Typical Per Diode Forward Voltage



Typical Per Diode Capacitance



Per Diode Current Derating



R4 (19-August 2020)

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

Corporate Headquarters & Customer Support Team

Central Semiconductor Corp.
145 Adams Avenue
Hauppauge, NY 11788 USA
Main Tel: (631) 435-1110
Main Fax: (631) 435-1824
Support Team Fax: (631) 435-3388
www.centrasemi.com

Worldwide Field Representatives:
www.centrasemi.com/wwreps

Worldwide Distributors:
www.centrasemi.com/wwdistributors

For the latest version of Central Semiconductor's **LIMITATIONS AND DAMAGES DISCLAIMER**, which is part of Central's Standard Terms and Conditions of sale, visit: www.centrasemi.com/terms